BSS83

MOSFET N-channel enhancement switching transistor

Rev. 03 — 21 November 2007

Product data sheet

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DESCRIPTION

Symmetrical insulated-gate silicon MOS field-effect transistor of the N-channel enhancement mode type. The transistor is sealed in a SOT143 envelope and features a low ON resistance and low capacitances. The transistor is protected against excessive input voltages by integrated back-to-back diodes between gate and substrate.

APPLICATIONS

- analog and/or digital switch
- · switch driver

PINNING

1 = substrate (b)

2 = source

3 = drain

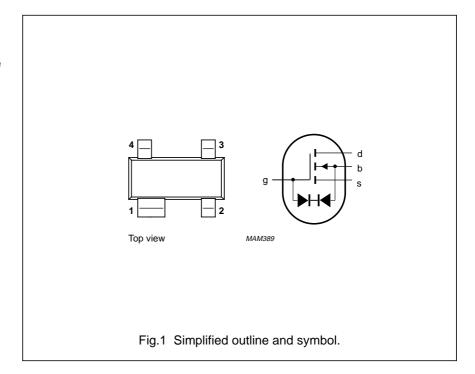
4 = gate

Note

1. Drain and source are interchangeable.

Marking code:

BSS83 = % M9



QUICK REFERENCE DATA

Drain-source voltage	V_{DS}	max.	10	V
Source-drain voltage	V_{SD}	max.	10	V
Drain-substrate voltage	V_{DB}	max.	15	V
Source-substrate voltage	V_{SB}	max.	15	V
Drain current (DC)	I _D	max.	50	mA
Total power dissipation up to T _{amb} = 25 °C	P_{tot}	max.	230	mW
Gate-source threshold voltage				
$V_{DS} = V_{GS}; V_{SB} = 0;$	M	>	0.1	V
$I_D = 1 \mu A$	$V_{GS(th)}$	<	2.0	V
Drain-source ON-resistance				
$V_{GS} = 10 \text{ V}; V_{SB} = 0; I_D = 0.1 \text{ mA}$	R_{DSon}	<	45	Ω
Feed-back capacitance				
$V_{GS} = V_{BS} = -15 \text{ V};$				
$V_{DS} = 10 \text{ V}; f = 1 \text{ MHz}$	C_{rss}	typ.	0.6	pF

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RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	V_{DS}	max.	10	V
Source-drain voltage	V_{SD}	max.	10	V
Drain-substrate voltage	V_{DB}	max.	15	V
Source-substrate voltage	V_{SB}	max.	15	V
Drain current (DC)	I_{D}	max.	50	mΑ
Total power dissipation up to $T_{amb} = 25 {}^{\circ}C^{(1)}$	P_{tot}	max.	230	mW
Storage temperature range	T_{stg}	-65 to -	+ 150	°C
Junction temperature	T;	max.	125	°C

THERMAL RESISTANCE

From junction to ambient in free $air^{(1)}$ $R_{th j-a} = 430 \text{ K/W}$

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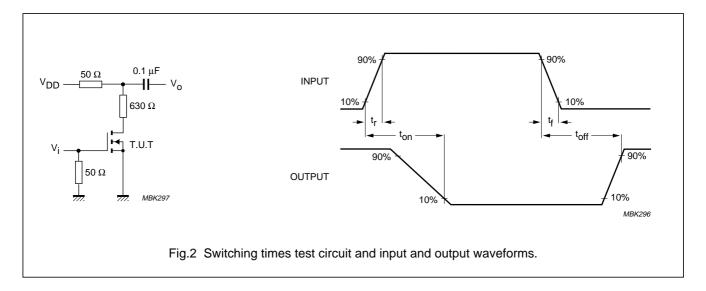
CHARACTERISTICS				
T _{amb} = 25 °C unless otherwise specified				
Drain-source breakdown voltage				
$V_{GS} = V_{BS} = -5 \text{ V}; I_D = 10 \text{ nA}$	$V_{(BR)DSX}$	>	10	V
Source-drain breakdown voltage				
$V_{GD} = V_{BD} = -5 \text{ V}; I_D = 10 \text{ nA}$	$V_{(BR)SDX}$	>	10	V
Drain-substrate breakdown voltage				
$V_{GB} = 0$; $I_D = 10$ nA; open source	$V_{(BR)DBO}$	>	15	V
Source-substrate breakdown voltage				
$V_{GB} = 0$; $I_D = 10$ nA; open drain	$V_{(BR)SBO}$	>	15	V
Drain-source leakage current				
$V_{GS} = V_{BS} = -2 \text{ V}; V_{DS} = 6.6 \text{ V}$	I_{DSoff}	<	10	nA
Source-drain leakage current				
$V_{GD} = V_{BD} = -2 \text{ V}; V_{SD} = 6.6 \text{ V}$	I_{SDoff}	<	10	nA
Forward transconductance at f = 1 kHz				
$V_{DS} = 10 \text{ V}; V_{SB} = 0; I_D = 20 \text{ mA}$	~	>	10	mS
	9fs	typ.	15	mS
Gate-source threshold voltage				
$V_{DS} = V_{GS}; V_{SB} = 0; I_D = 1 \mu A$	Vasus	>	0,1	V
	$V_{GS(th)}$	<	2,0	V
Drain-source ON-resistance				
$I_D = 0.1 \text{ mA};$				
$V_{GS} = 5 \text{ V}; V_{SB} = 0$	R_{DSon}	<	70	Ω
$V_{GS} = 10 \text{ V}; V_{SB} = 0$	R_{DSon}	<	45	Ω
$V_{GS} = 3.2 \text{ V}; V_{SB} = 6.8 \text{ V} \text{ (see Fig.4)}$	P	$>$ 0,1 V 2,0 V $>$ S(th) $<$ 2,0 V $>$ Son $<$ 70 Ω Son $<$ 45 Ω typ. 80 Ω Son $<$ 120 Ω	Ω	
	DSon	<	120	Ω
Gate-substrate zener voltages				
$V_{DB} = V_{SB} = 0$; $-I_G = 10 \mu A$	$V_{Z(1)}$	>	12,5	V
$V_{DB} = V_{SB} = 0$; $+I_{G} = 10 \mu A$	$V_{Z(2)}$	>	12,5	V
Capacitances at f = 1 MHz				
$V_{GS} = V_{BS} = -15 \text{ V}; V_{DS} = 10 \text{ V}$				
Feed-back capacitance	C_{rss}	typ.	0,6	pF
Input capacitance	C_{iss}	typ.	1,5	pF
Output capacitance	C_{oss}	typ.	1,0	pF
Switching times (see Fig.2)				
$V_{DD} = 10 \text{ V}; V_i = 5 \text{ V}$	t_{on}	typ.	1,0	ns
	t_{off}	typ.	5,0	ns

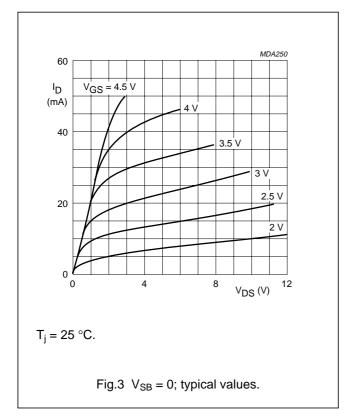
Note

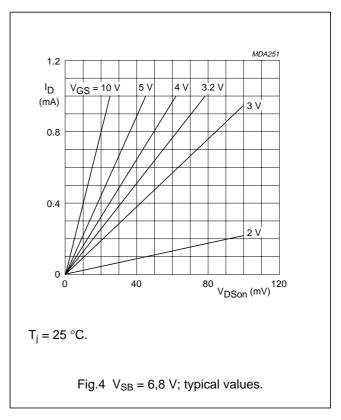
1. Device mounted on a ceramic substrate of 8 mm \times 10 mm \times 0,7 mm.

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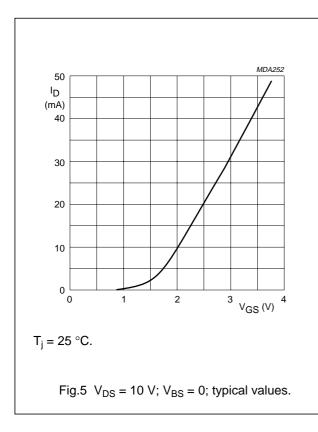
Pulse generator:

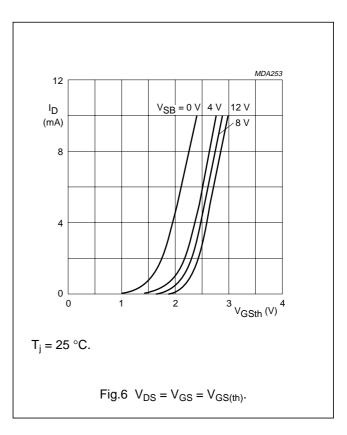


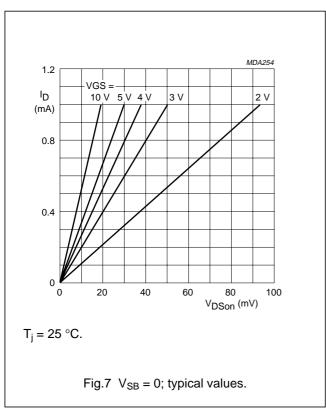




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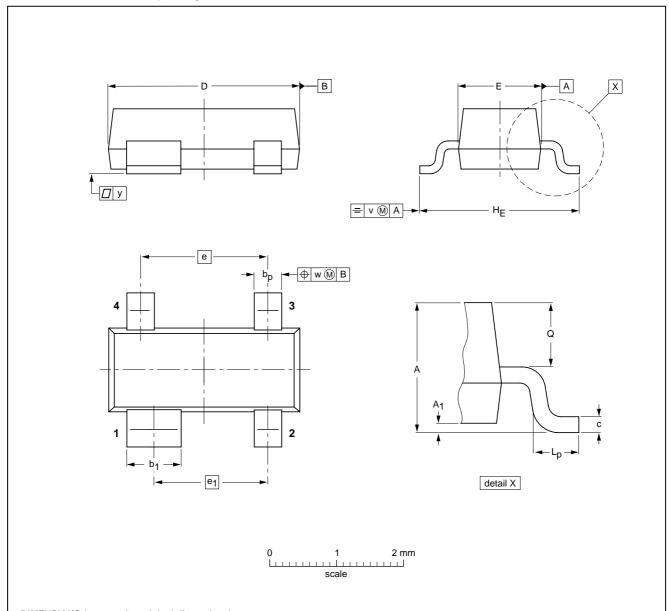


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PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

SOT143B



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	b ₁	С	D	E	е	e ₁	HE	L _p	Q	v	w	у
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT143B					97-02-28

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Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Revision history

Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BSS83_N_3	20071121	Product data sheet	-	BSS83_CNV_2
Modifications:	 Page 2; colu 	mn 2; Marking code; row 1 cha	anged	
BSS83_CNV_2	19910401	Product specification	-	-

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